

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4091660

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ICHIRO SATO	02/12/2009
YASUHISA NAKAJIMA	02/09/2009
RECEIVING PARTY DATA	
Name:	SONY CORPORATION
Street Address:	1-7-1 KONAN, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	108-0075
Name:	SONY ESPANA S.A.
Street Address:	SABINO DE ARANA 52
City:	BARCELONA
State/Country:	SPAIN
Postal Code:	08028
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15288541
CORRESPONDENCE DATA	
Fax Number:	(908)654-0415
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(908) 518-6355
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Correspondent Name:	LDLK&M
Address Line 1:	600 SOUTH AVENUE WEST
Address Line 4:	WESTFIELD, NEW JERSEY 07090
ATTORNEY DOCKET NUMBER:	SONYJP 3.0-1747 CON CON C
NAME OF SUBMITTER:	MELINDA C. CORMIER
SIGNATURE:	/Melinda C. Cormier/
DATE SIGNED:	10/11/2016

Total Attachments: 4

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Docket No.: SONYJP 3,0-1747
 Sony Ref. No.: S08P1787US00J

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

**DISPLAY DEVICE, PROGRAM INFORMATION DISPLAY METHOD IN DISPLAY DEVICE, RECEIVING DEVICE,
 AND SIGNAL TRANSMISSION METHOD IN RECEIVING DEVICE**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese Corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan and Sony Espana S.A., a Spanish Corporation with offices at Sabino de Arana 52, 08028 Barcelona, Spain (hereinafter referenced as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the ASSIGNEES of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 12/291,592; Filing Date: November 12, 2008.

This assignment executed on the dates indicated below.

Ichiro SATO

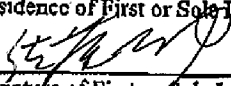
Name of First or Sole Inventor

Execution Date of U.S. Patent Application

Barcelona, Spain

Residence of First or Sole Inventor

12 February 2009



Signature of First or Sole Inventor

Date of this Assignment

PATENT

REEL: 039986 FRAME: 0033

Docket No.: SONYJP 3.0-1747
Sony Ref. No.: S08P1787US00J
Page 2

Yasuhisa NAKAJIMA

Name of Second Joint Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan

Residence of Second Joint Inventor

Signature of Second Joint Inventor

Date of this Assignment

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

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NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the ASSIGNEES of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

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This assignment executed on the dates indicated below.

Ichiro SATO

Name of First or Sole Inventor

Execution Date of U.S. Patent Application

Barcelona, Spain

Residence of First or Sole Inventor

Signature of First or Sole Inventor

042299 1.1000

Date of this Assignment

PATENT

REEL: 039986 FRAME: 0035

Yasuhisa NAKAJIMA

Name of Second Joint Inventor

9. Feb. 2009

Execution Date of U.S. Patent Application

Kanagawa, Japan

Residence of Second Joint Inventor

Yasuhisa Nakajima

Signature of Second Joint Inventor

9 Feb. 2009

Date of this Assignment